



- NOTES:
- MATERIAL : NA-311B/BLACK/Al<sub>2</sub>O<sub>3</sub>(90%MIN.)
  - CAMBER : 30.00 MICRON MAX. T.B.D.
  - PLATING THICKNESS:  
 ELCTRO Ni : 1.27 ~ 8.89 MICRON.  
 ELCTRO Au : 0.70 ~ 1.20 MICRON.
  - CONNECTION:  
 (#3-a), (#1-b-c), (#2-#4-S/R)
  - STRESS RELAXATION DESIGN SHALL BE APPLIED ON THIS ITEM.
  - THICKNESS OF BUMP AREA SHALL BE 30.00 ~ 60.00 MICRON INCLUDE MP-21,23.
  - CONCAVITY ON FILLED METALLIZATION TO BE ALLOWED.
  - PART TO BE SHOWN AS SIDE METALLIZED PATTERN.
  - SEALING METHOD OF THIS PRODUCT SHALL BE SEAM WELD.

TOLERANCE	REVISION	SEE ATTACHED EXCEPTIONS SHEET.				TITLE	
±1% N.L.T.±0.13 ANGLES	SCALE	DIMENSION	PROJECTION	CUSTOMER DWG NO.	REV.		3.2X2.5 CRYSTAL
	22 : 1	mm	3rd				
MATERIAL	APPROVED	CHECKED	ENGRG	CHECKED	DESIGNED		PART NO.
90%MIN.A12O3 (NA-311B BLACK)	Shigetomi	Inoue	Ohba	Kumura	Sugi		S2532XTAL2
	Nov.27.03	Nov.27.03	Nov.27.03	Nov.27.03	Nov.27.03		REV. 0
							DWG NO.
							SHT/OF 1/6